

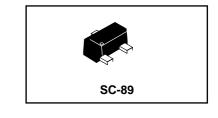


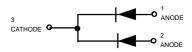
Common Cathode Silicon Dual Switching Diode

This Common Cathode Silicon Epitaxial Planar Dual Diode is designed for use in ultra high speed switching applications. This device is housed in the SC–89 package which is designed for low power surface mount applications, where board space is at a premium.

- Fast trr
- Low C_D
- Available in 8 mm Tape and Reel
- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

LDAN222T1G S-LDAN222T1G





ORDERING INFORMATION

Device	Marking	Shipping
LDAN222T1G S-LDAN222T1G	N9	3000/Tape&Reel
LDAN222T3G S-LDAN222T3G	N9	10000/Tape&Reel

MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	80	Vdc
Peak Reverse Voltage	V _{RM}	80	Vdc
Forward Current	١F	100	mAdc
Peak Forward Current	IFM	300	mAdc
Peak Forward Surge Current	IFSM(1)	2.0	Adc

THERMAL CHARACTERISTICS

Rating	Symbol	Мах	Unit
Power Dissipation	PD	150	mW
Junction Temperature	Тј	150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

1. $t = 1 \ \mu S$

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$)

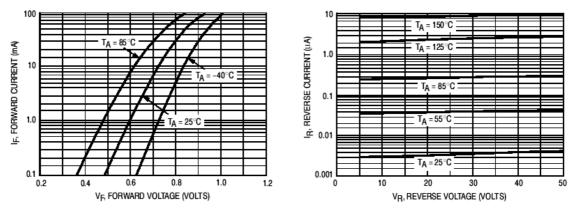
Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	IR	V _R = 70 V	_	0.1	μAdc
Forward Voltage	٧F	I _F = 100 mA	—	1.2	Vdc
Reverse Breakdown Voltage	VR	I _R = 100 μA	80	—	Vdc
Diode Capacitance	CD	V _R = 6.0 V, f = 1.0 MHz	—	3.5	pF
Reverse Recovery Time	t _{rr} (2)	IF = 5.0 mA, VR = 6.0 V, RL = 100 Ω , Irr = 0.1 IR	_	4.0	ns

2. t_{rr} Test Circuit on following page.





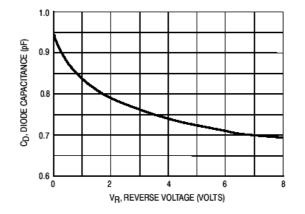
LDAN222T1G, S-LDAN222T1G

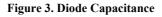


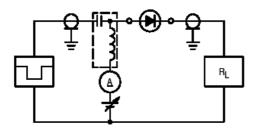
Electrical characteristic curves



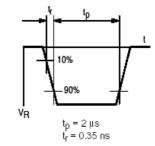
Figure 2. Reverse Current



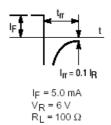




RECOVERY TIME EQUIVALENT TEST CIRCUIT



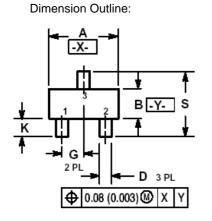




OUTPUT PULSE



LDAN222T1G, S-LDAN222T1G

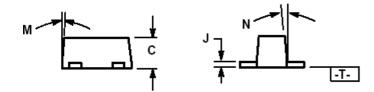


SC-89

NOTES:

1.DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982

2.		MILLIMETERS			INCHES			ERS
	DIM	MIN	NOM	MAX	MIN	NOM	MAX	LEAD
3.]	Α	1.50	1.60	1.70	0.059	0.063	0.067	3 LEAD
FI	В	0.75	0.85	0.95	0.030	0.034	0.040	CKNESS
IS	С	0.60	0.70	0.80	0.024	0.028	0.031	
10	D	0.23	0.28	0.33	0.009	0.011	0.013	
М	G	0.50 BSC			0.020 BSC			
4.4	H	0.53 REF			0.021 REF			3C-02.
ч.·	7	0.10	0.15	0.20	0.004	0.006	0.008	JC-02.
	K	0.30	0.40	0.50	0.012	0.016	0.020	
	L	1.10 REF			0.043 REF			
	М			10 °			10 °	
	N			10 °			10 °	
	S	1.50	1.60	1.70	0.059	0.063	0.067	



Soldering Footprint:

